

# TECKNIT 0002

## ONE COMPONENT FAST CURE ELECTRICALLY CONDUCTIVE SILICONE SEALANT



### Customer Value Proposition:

TECKNIT 0002 is a silver filled, one-component conductive silicone, designed for use as a fillet, gap filler and seam sealant on electrical enclosures for EMI shielding or electrical grounding. Minimum recommended bond line for TECKNIT 0002 is 0.005 inches (0.13 mm). In addition, TECKNIT 0002 may be used for EMI gasket repair, bonding, and attachment in applications where moderate strength (150 psi) is required. TECKNIT 0002's moisture cure silicone polymer system allows it to cure to the touch in 2 hrs and provides a flexible and resilient conductive and environmental seal over a wide range of application temperatures.

Care must be taken when using TECKNIT 0002 on sensitive substrates as a trace amount of acetic acid is emitted during cure which may damage electrical circuitry. Ventilation may also be required when using TECKNIT 0002 as the acetic acid released during cure emits a strong odor. Typical applications include man portable electronics, radar and communication systems, EMI vents, military ground vehicles, and shelters.

### Contact Information:

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### Features and Benefits:

- One component
- Silver filler
- Moisture cure silicone
- Acetic acid cure mechanism
- Medium paste
- Easy to use, no weighing or mixing required.
- Excellent conductivity 0.010 ohm-cm.
- 5 minute working life, rapid skin formation, requires no pressure during curing, wide range of application temperatures.
- Quick curing, 2 hrs handling time, 72 hrs for full cure properties. Primerless system
- Easy to dispense, apply and spread, can be used on overhead and vertical surfaces.



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## TECKNIT 0002 - Product Information

**Table 1 Typical Properties**

TECKNIT 0002		
Typical Properties	Typical Values	Test Method
Polymer	Silicone	N/A
Filler	Silver	N/A
Mix Ratio, A : B (by weight)	1-part	N/A
Color	Beige	N/A (Q)
Consistency	Medium Paste	N/A (Q)
Maximum DC Volume Resistivity	0.010 ohm-cm	QAP-1038* (Q/C)
Minimum Lap Shear Strength	150 psi (1034 kPa)	CHO-95-40-5300* (Q/C)
Minimum Peel Strength	2.0 lb./inch (350 N/m)	CHO-95-40-5302* (Q)
Specific Gravity	3.1	QAP-1101F* (Q/C)
Hardness	51 Shore A	QAP-1102G* (Q/C)
Continuous Use Temperature	- 59°C to 204°C (-75 °F to 400 °F)	N/A (Q)
Elevated Temperature Cure Cycle	None	N/A
Room Temperature Cure	72 hours**	N/A (Q)
Working Life	5 minutes	N/A (Q)
Shelf Life, unopened	5.5 months @ 25°C (77°F)	N/A (Q)
Minimum thickness recommended	0.005 in (0.13 mm)	N/A
Maximum thickness recommended	0.125 in (3.18 mm)	N/A
Volatile Organic Content (VOC)	31 g/l	Calculated
Theoretical Coverage Area at 0.010" Thick per Pound (454 grams)	900 in <sup>2</sup> (5806 cm <sup>2</sup> )	N/A
Theoretical Coverage - Length of an 1/8" Diameter Bead per Pound (454 grams)	60 feet (18.3 m)	N/A

**Note:** N/A - Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test.

\* This test Method is available from Parker Chomerics.

\*\* Cure is sufficient for handling in 2 hours. Full specification properties are developed after 72 hours.

**Table 2 Ordering Information**

Product	Weight (grams)	Packaging	Part Number	Primer Included
TECKNIT 0002	56	0.75 fluid ounce aluminum foil tube	72-00002	Not Required

**Note:** Package includes spreading tool and instructions.

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

[www.chomerics.com](http://www.chomerics.com)  
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